

Technical Data Sheet

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HELOXY™ Modifier 62

Product Description

HELOXY[™] Modifier 62 is a commercial grade of o-cresyl glycidyl ether. A low viscosity aromatic monoepoxide, its primary use is the viscosity reduction of conventional epoxy resin systems.

Benefits

- Reduces viscosity of higher molecular weight aromatic epoxy resins
- Excellent retention of mechanical and chemical resistance cured state properties relative to other monoepoxides
- · Low volatility
- Improves substrate and filler wetting of conventional formulations

Sales Specification

| Property | Units | Value | Test Method/Standard |
|--------------------|---------|---------|----------------------|
| Weight per Epoxide | g/eq | 175-195 | ASTM D1652 |
| Viscosity at 25°C | cP | 5-10 | ASTM D445 |
| Color | Gardner | 2 | ASTM D1544 |
| Epichlorohydrin | mg/kg | 10 | SMS 2445 |
| | | | |

Typical Properties

| Property | Units | Value | Test Method/Standard |
|----------|---------|---------|----------------------|
| Density | lbs/gal | 8.9-9.1 | ASTM D1475 |
| | | | |

General Information

HELOXY 62 is compatible with virtually all classes of epoxy resins used in thermoset plastics and protective coatings applications.

As with any monoepoxide, modification of basic epoxy resins with HELOXY 62 reduces the average epoxide functionality of the mixture thereby lowering cured state chemical and solvent resistance and thermal performance. However, due to the highly aromatic structure of HELOXY 62, compromises in these

properties are found to be minimized relative to those associated with other monoepoxides commonly used in the viscosity reducing modification of epoxy formulations.

The relatively low molecular weight of HELOXY 62 makes it among the most efficient of the aromatic monoepoxides in reducing viscosity of basic epoxy resins. A comparison of this characteristic to that of other representative Heloxy modifiers is illustrated in Figure 1. Since the degree to which performance properties are affected depends on the amount of Heloxy 62 in the formulation, the amount used should be limited to that necessary to yield the required viscosity reduction. The maximum recommended quantity of Heloxy 62 is about 30 percent of the resin portion. Curing agents that are recommended for satisfactory crosslinking of unmodified basic liquid epoxy resins can also be used with compositions containing HELOXY 62. Since the average weight per epoxide of HELOXY 62 is virtually identical to that of commercial liquid bisphenol A-based epoxy resins, differences in epoxy content due to HELOXY 62 modifications are normally insignificant and adjustments in curing agent combining ratio to maintain proper stoichiometry with HELOXY 62 modified blends is usually unnecessary.

As previously stated, the cured state properties at room temperature of epoxy formulations are not seriously affected when viscosity reduction is attained via HELOXY 62 unless excessive amounts are used. However, performance at elevated service temperatures may be reduced considerably. Data listed in Table 1 illustate the effect of HELOXY 62 on systems cured with various curing agents, including conventional polyamines, anhydrides, and EPIKURETM 3072 Curing Agent. A preblend of HELOXY 62 and a standard bisphenol A based epoxy resin at a viscosity selected for ease of handling is available as EPONTM Resin 813. For information on the properties and suggested uses of this resin, please consult the appropriate product bulletin.

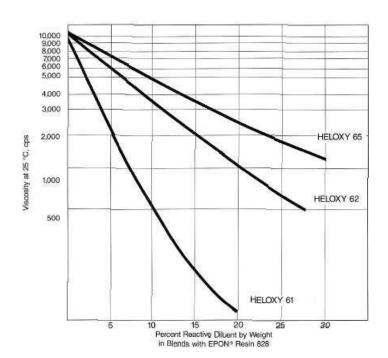


Figure 1 / Viscosity dilution effectiveness of HELOXY Modifiers

Performance Properties

Table 1 / Typical Properties of epoxy resin systems containing HELOXY Modifier 62

| | Method | <u>Units</u> | <u>A</u> | <u>B</u> | <u>C</u> | D | <u>E</u> | <u>F</u> |
|-------------------------------------|--------------|--------------|----------|----------|----------|--------|----------|----------|
| Composition | | | | | | | | |
| EPON Resin 828 | | pbw | 100 | 90 | 80 | 77 | 70 | 77 |
| HELOXY Modifier 62 | | pbw | _ | 10 | 20 | 23 | 30 | 23 |
| EPIKURE 3234 | | pbw | 12.9 | 13 | 13.5 | _ | _ | _ |
| EPIKURE 3072 Curing Agent | | pbw | _ | _ | _ | 35 | 35 | _ |
| Hexahydrophthalic Anhydride | | pbw | _ | _ | _ | - | _ | 78 |
| Diethylaminoethanol | | pbw | _ | - | - | _ | _ | 0.5 |
| Handling Properties at 25°C | | | | | | | | |
| Viscosity, Resin Portion | | сР | 13,250 | 3,100 | 1,060 | 1,000 | 470 | 1,000 |
| Gel time, 100g @ 23 °C | | min. | 44 | 43 | 45 | 52 | 57 | _ |
| 1/4 in. thick, @ 93 °C | | min. | _ | _ | _ | _ | _ | 75 |
| Peak Exotherm, 100g @ 23 °C | | °C | 223 | 223 | 211 | 168 | 147 | - |
| Cured State Properties ¹ | | | | | | | | |
| Heat Deflection Temperature | ASTM D648 | °C | 103 | 86 | 69 | 64 | 58 | 98 |
| Tensile strength, Ultimate | ASTM D638 | psi | 10,050 | 11,400 | 11,300 | 9,600 | 8,400 | 13,300 |
| Tensile elongation at Break | | % | 3.7 | 5.3 | 6.3 | 5.2 | 10.5 | 5.9 |
| Tensile Modulus, Initial | | ksi | 450 | 500 | 570 | 460 | 430 | 550 |
| Flexural Strength, Ultimate | ASTM D790 | psi | 18,700 | 20,200 | 20,900 | 14,300 | 12,400 | 22,000 |
| Flexural Modulus, Initial | | ksi | 470 | 510 | 580 | 420 | 360 | 530 |
| Compressive Strength, Ultimate | ASTM D695 | psi | 33,400 | 27,900 | 30,300 | 19,000 | 19,000 | 34,000 |
| Compressive Yield Strength | | psi | 15,650 | 14,900 | 15,500 | 13,600 | 11,700 | 16,400 |
| Izod Impact – notch | ASTM D256 | ft.•lb./inch | 0.45 | 0.45 | 0.40 | 0.47 | 0.43 | 0.38 |
| Weight Loss, 24 hrs. @ 150 | | % | 0.24 | 0.8 | 1.55 | 1.44 | 2.06 | 0.15 |

°C

Percent Absorbtion ²

| Water | | % | | | | | | |
|----------------------------------|--------------|---|-------|-------|-------|-------|-------|-------|
| 24 hrs. | | | 0.168 | 0.08 | 0.07 | 0.17 | 0.19 | 0.07 |
| 1 week | | | 0.38 | 0.26 | 0.25 | 0.47 | 0.52 | 0.20 |
| 5% Acetic Acid | | % | | | | | | |
| 24 hrs. | | | 0.21 | 0.20 | 0.19 | 0.77 | 0.82 | 0.07 |
| 1 week | | | 0.58 | 0.61 | 0.74 | 1.97 | 2.13 | 0.21 |
| Solvent ³ | | % | | | | | | |
| 24 hrs. | | | 0.02 | -0.08 | -0.05 | 7.55 | 10.8 | 0.07 |
| 1 week | | | 0.05 | -0.17 | -0.09 | _ | _ | 0.51 |
| Dielectric Constant ⁴ | ASTM D150 | | 3.91 | 3.80 | 3.83 | 3.65 | 3.68 | 3.48 |
| Dissipation Factor ⁴ | 2100 | | 0.031 | 0.020 | 0.017 | 0.013 | 0.013 | 0.011 |

¹Determined on 0.125 thick specimens at 23 °C. Systems A through C cured 16 hours at 25 °C plus 2 hours at 100 °C. Systems D and E cured 14 days at 25 °C. System F cured 2 hours at 93 °C plus 2 hours at 200 °C.

Safety, Storage & Handling

Please refer to the MSDS for the most current Safety and Handling information.

Please refer to the Momentive web site for Shelf Life and recommended Storage information.

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Packaging

Available in bulk and drum quantities.

²Weight gain of 3 inch x 1 inch x 0.125 inch specimens totally immersed in reagent at 25 °C.

³50:50 by weight mix of isopropanol and xylene.

⁴Determined at 106 hertz.

Contact Information

For product prices, availability, or order placement, call our toll-free customer service number at: 1-877-859-2800

For literature and technical assistance, visit our website at: www.momentive.com

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